Equipment

Chip Die Bonder

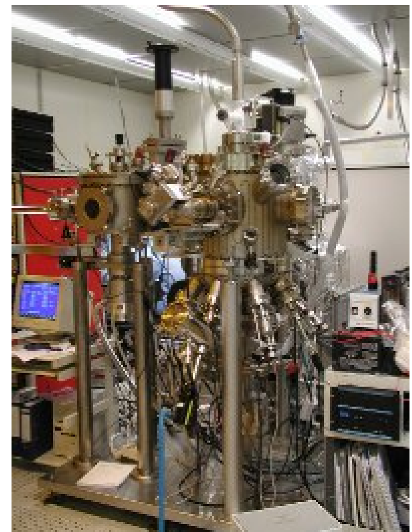
Helios NanoLab DualBeam System

ECR-RIE System

ICP-RIE System

Leybold L560

Molecular Beam Epitaxy (MBE) System

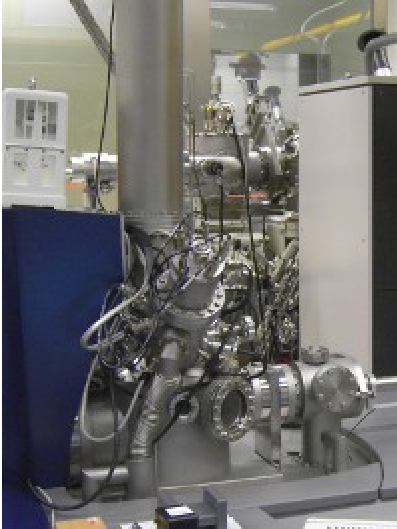


Reactive Ion Etch System

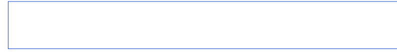
Hitachi S-900 SEM

Hitachi S-4100 SEM

Secondary Ion Mass Spectrometry (SIMS) System



FEI Titan 80-300 TEM



BesTec UHV Sputtering System

Kulicke & Soffa Manual Wire Bonder

Letzte Änderung: 10.11.2009